

Line Number	Hits	Search Text	DB	Time Stamp
1	0	hiroki-tsutomo.in.	USPAT; US-PGPUB	2003/11/10 12:20
2	4	hiroki-tsutomo.in.	USPAT; US-PGPUB	2003/11/10 12:21
3	4	hiroki-tsutomus.in.	USPAT; US-PGPUB	2003/11/10 12:21
4	0	hiroki-tsutomi-.in.	USPAT; US-PGPUB	2003/11/10 12:22
5	2115	((414/935) or (414/939) or (118/719) or (136/345..31) or (156/345..32)).CCLS.	USPAT; US-PGPUB	2003/11/10 12:22
6	0	("5and8pd->20030/01").PN.	USPAT; US-PGPUB	2003/11/10 12:24
7	86	((414/935) or (414/939) or (118/719) or (156/345..31) or (156/345..32)).CCLS.) and @pd->20030701	USPAT; US-PGPUB	2003/11/10 12:24
8	116	(414/9..ccls. 118/\$.ccls. 156/345..ccls.) and (articulat\$3 with linear\$3)	USPAT; US-PGPUB	2003/07/28 08:27
9	54	(farm hand robot) with (articulat\$3 with linear\$3 with extend\$3)	USPAT; US-PGPUB	2003/07/27 19:29
10	1	("5993141").PN.	USPAT; US-PGPUB	2003/07/28 08:23
11	5	5993141.URPN.	USPAT	2003/07/28 08:23
12	28	("400978" "4410209" "4566726" "4601627" "4775281" "4875824" "5080549" "5100502" "5147175" "5286296" "5382128" "5439547" "5474410" "5479108" "5562387" "5636963" "5647626" "5647724" "5669644" "5697749" "5755449" "5789878" "5900105" "5950495" "5993141" "6040162" "6073366" "6224319").PN.	USPAT	2003/07/27 19:30
13	5	5993141.URPN.	USPAT	2003/07/28 08:23
14	5	5993141.URPN.	USPAT	2003/07/28 08:23
15	221	(414/\$.ccls. 118/\$.ccls. 156/345..ccls.) and (articulat\$3 same linear\$3)	USPAT; US-PGPUB	2003/07/28 08:28
16	151	(414/\$.ccls. 118/\$.ccls. 156/345..ccls.) and (articulat\$3 same linear\$3 same (hand robot arm effector blade))	USPAT; US-PGPUB	2003/07/28 08:28
17	116	(414/\$.ccls. 118/\$.ccls. 156/345..ccls.) and (articulat\$3 with linear\$3)	USPAT; US-PGPUB	2003/07/28 08:27
18	68	((414/\$.ccls. 118/\$.ccls. 156/345..ccls.) and (articulat\$3 same linear\$3 same (hand robot arm effector blade))) not ((414/\$.ccls. 118/\$.ccls. 156/345..ccls.) and (articulat\$3 with linear\$3))	USPAT; US-PGPUB	2003/07/28 08:27
19	0	(c23c0168.ipc.) and (articulat\$3 same linear\$3 same (hand robot arm effector blade))	EPO; JPO; DERWENT	2003/07/28 08:31
20	0	(c23c0168.ipc.) and (articulat\$3 same linear\$3 same (hand robot arm effector blade))	EPO; JPO; DERWENT	2003/07/28 08:29
21	10	(c23c0168.ipc.) and (linear\$3 same (hand robot arm effector blade))	EPO; JPO; DERWENT	2003/07/28 08:29
22	213	(articulat\$3 same linear\$3 same (hand robot arm effector blade))	EPO; JPO; DERWENT	2003/07/28 08:31
23	3	(articulat\$3 same linear\$3 same (hand robot arm effector blade)) same (wafer substrate semiconductor)	EPO; JPO; DERWENT	2003/07/28 08:40
24	70	((reciprocat\$5 extend\$3 retract\$4) same linear\$3 same (hand robot arm effector blade)) same (wafer substrate semiconductor)	EPO; JPO; DERWENT	2003/07/28 08:41
25	654	((reciprocat\$5 extend\$3 retract\$4) same linear\$3 same (hand robot arm effector blade)) same (wafer substrate semiconductor)	USPAT; US-PGPUB	2003/07/28 09:01
26	70	((reciprocat\$5 extend\$3 retract\$4) same linear\$3 same (hand robot arm effector blade)) same (wafer substrate semiconductor)	EPO; JPO; DERWENT	2003/07/28 08:41

172	((reciprocat\$5 extend\$3 retract\$4) with linear\$3 with (hand robot arm effector blade) same (wafer substrate semiconductor))	USPAT; US-PGPUB	2003/07/28 09:52
25	4907931.URPN.	USPAT	2003/07/28 09:21
9	"3n03527" "4103232" "4407627" ; "441853" "4457664" "4655584" "4695215" "4746256" "4752898".PN.	USPAT	2003/07/28 10:37
25	4695215.URPN.	USPAT	2003/07/28 09:26
13	((44552504") or ("4454106") or ("4908095") or ("5011366") or ("5064340") or ("5206380") or ("5655060") or ("5746565") or ("5823736") or ("5989346") or ("6051101") or ("6155/68") or ("6164994")),PN.	USPAT; US-PGPUB	2003/07/28 10:47
11	5306380.URPN.	USPAT	2003/07/28 09:55
13	5823736.URPN.	USPAT	2003/07/28 10:40
8	"3817402" : "4591044" "4776745" "5.97C9" "5345639" "5374147" "5445491" "5540535".PN.	USPAT	2003/07/28 10:42
29	414/6209.cccls. and (wafer semiconductor substrate)	USPAT; US-PCIPUB	2003/07/28 10:58
0	6331093.URPN.	USPAT	2003/07/28 10:54
7	"4816098" "5823736" "5879128" "5879460" ! "5883017" "5934856" "5989346".PN.	USPAT	2003/07/28 10:54
0	414/.222.04.cccls. and (wafer semiconductor substrate)	USPAT; US-PGPUB	2003/07/28 10:59
21	414/222.04.cccls. and (wafer semiconductor substrate)	USPAT; US-PGPUR	2003/07/28 10:59
/	414/222.05.cccls. and (wafer semiconductor substrate)	USPAT; US-PCIPUB	2003/07/28 11:00
8	414/222.06.cccls. and (wafer semiconductor substrate)	USPAT; US-PGPUB	2003/07/28 11:00
34	(414/222.04.cccls. and (wafer semiconductor substrate)) (414/222.05.cccls. and (wafer semiconductor substrate)) (414/222.06.cccls. and (wafer semiconductor substrate))	USPAT; US-PGPUR	2003/07/28 11:00